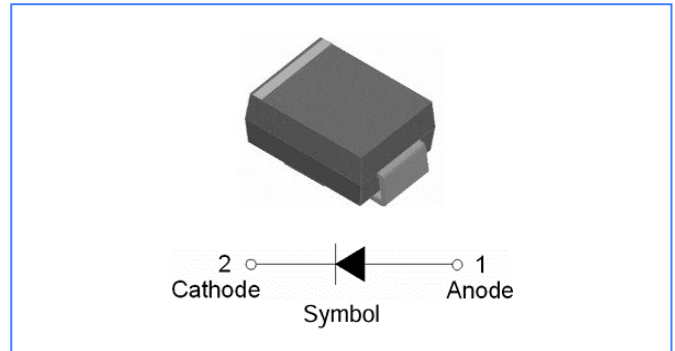


SS52 thru SS520 SMB

FEATURES

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering: 260°C/10 seconds at terminals



Mechanical Data

- Case: JEDEC DO-214AA molded plastic
- Terminals: Solder plated, solderable per JESD22-B102D
- Polarity: Laser band denotes cathode end

Major Ratings and Characteristics

$I_{F(AV)}$	5.0A
V_{RRM}	20 V to 200 V
I_{FSM}	150A
V_F	0.55V, 0.70V, 0.85V, 0.95V
$T_{j\ max.}$	150 °C

Maximum Ratings & Thermal Characteristics

(TA = 25 °C unless otherwise noted)

Items	Symbol	SS52	SS53	SS54	SS55	SS56	SS58	SS510	SS515	SS520	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current	$I_{F(AV)}$	5.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	150									A
Voltage rate of change (rated VR)	dv/dt	10000									V/μs
Thermal resistance from junction to lead ⁽¹⁾	$R_{θJL}$	25									°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-55 TO +150									°C

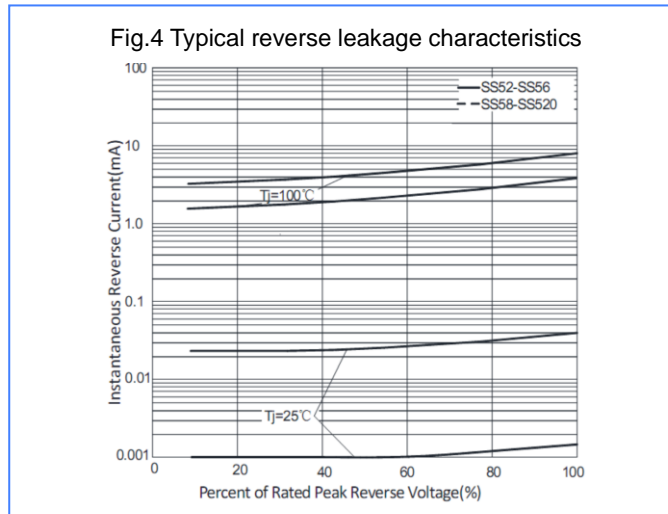
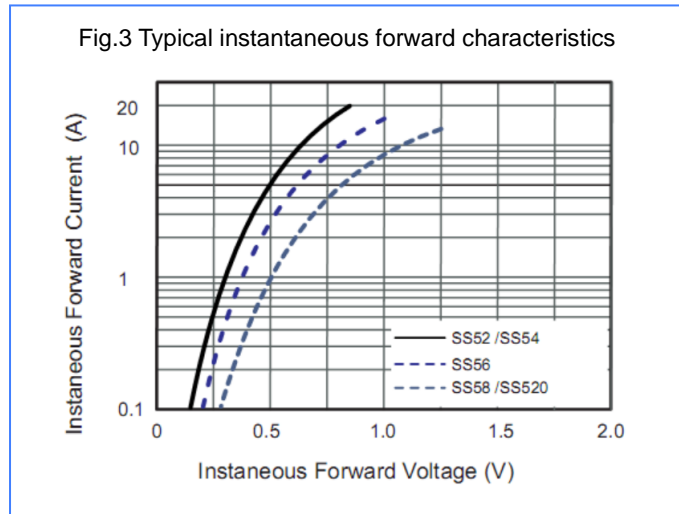
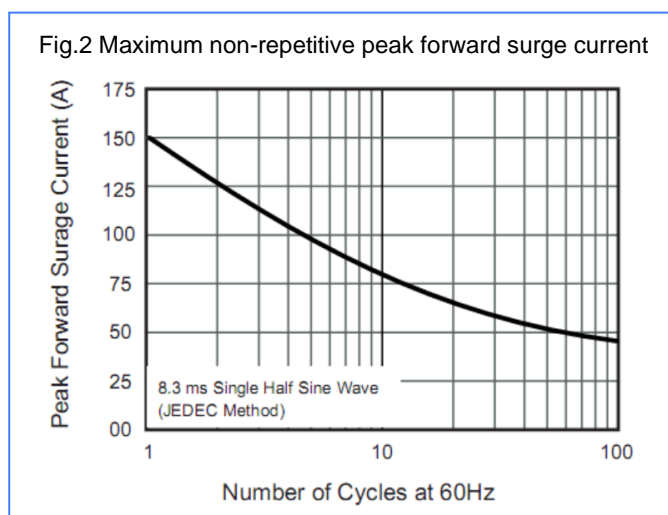
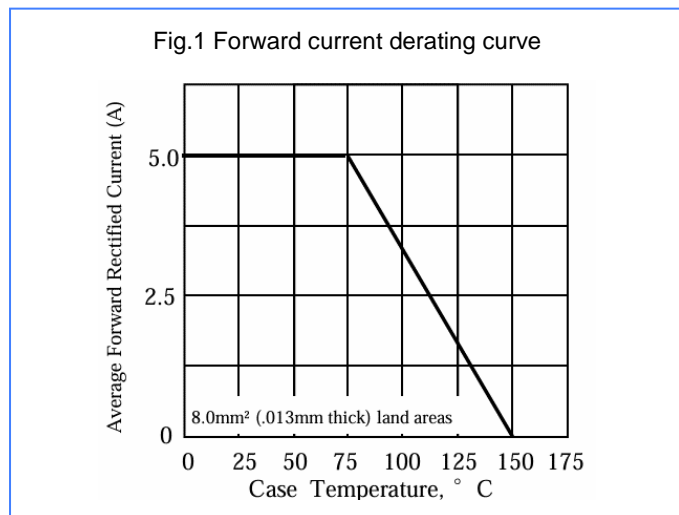
Note 1: Mounted on P.C.B. with 0.28" x 0.28" (7.0 x 7.0mm) copper pad areas.

Electrical Characteristics (TA = 25 °C unless otherwise noted)

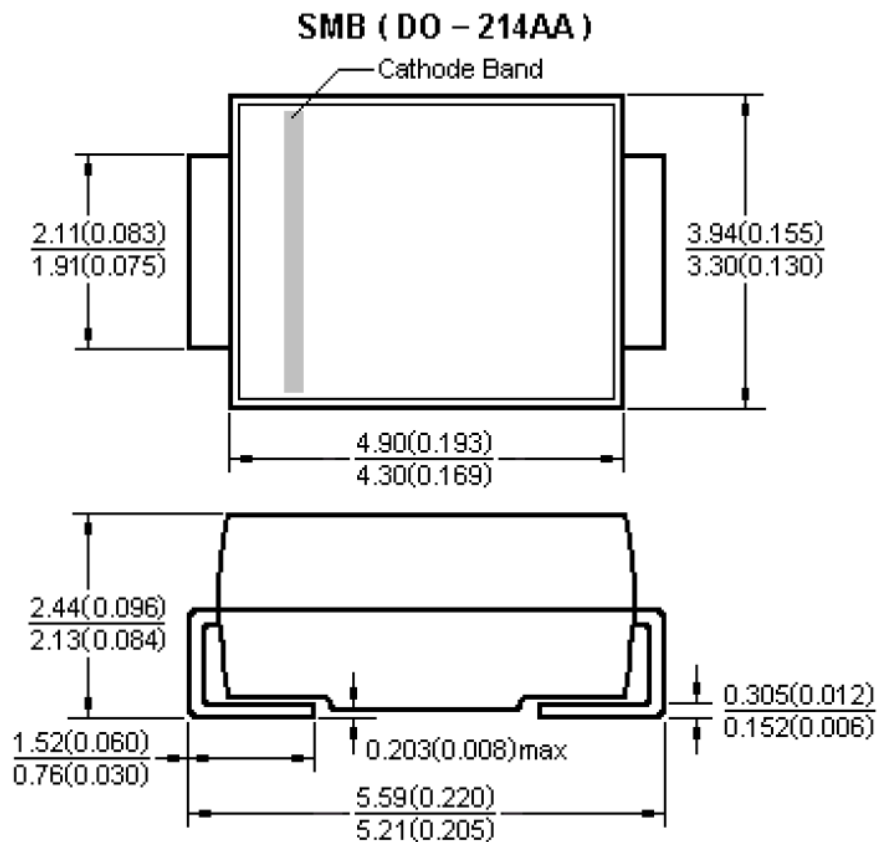
Items	Test conditions	Symbol	SS52~54	SS55~56	SS58~510	SS515~520	UNIT
Instantaneous forward voltage	IF=5.0A ⁽²⁾	V _F	0.55	0.70	0.85	0.95	V
Reverse current	V _R =V _{DC}	T _J =25°C	0.5		0.3		mA
		T _J =100°C	10.0		5.0		

Note 2: Pulse test:300μs pulse width,1% duty cycle.

Typical Characteristics



Package Outline (SMB DO-214AA)



Dimensions in millimeters and (inches)

Disclaimer

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.